

**/ Descriptions**

TO-252          N      MOS          N-CHANNEL MOSFET in a TO-252 Plastic Package.

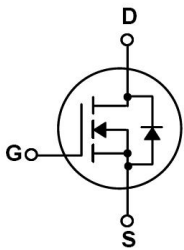
**/ Features**

100%  
Low gate charge, low  $R_{ds(on)}$ , fast switching, Low Reverse transfer capacitances, 100% Single Pulse avalanche energy Test.

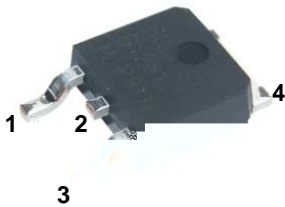
**/ Applications**

Power switch circuit of Video doorphone.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 G          PIN 2 D          PIN 3 S          PIN 4 D

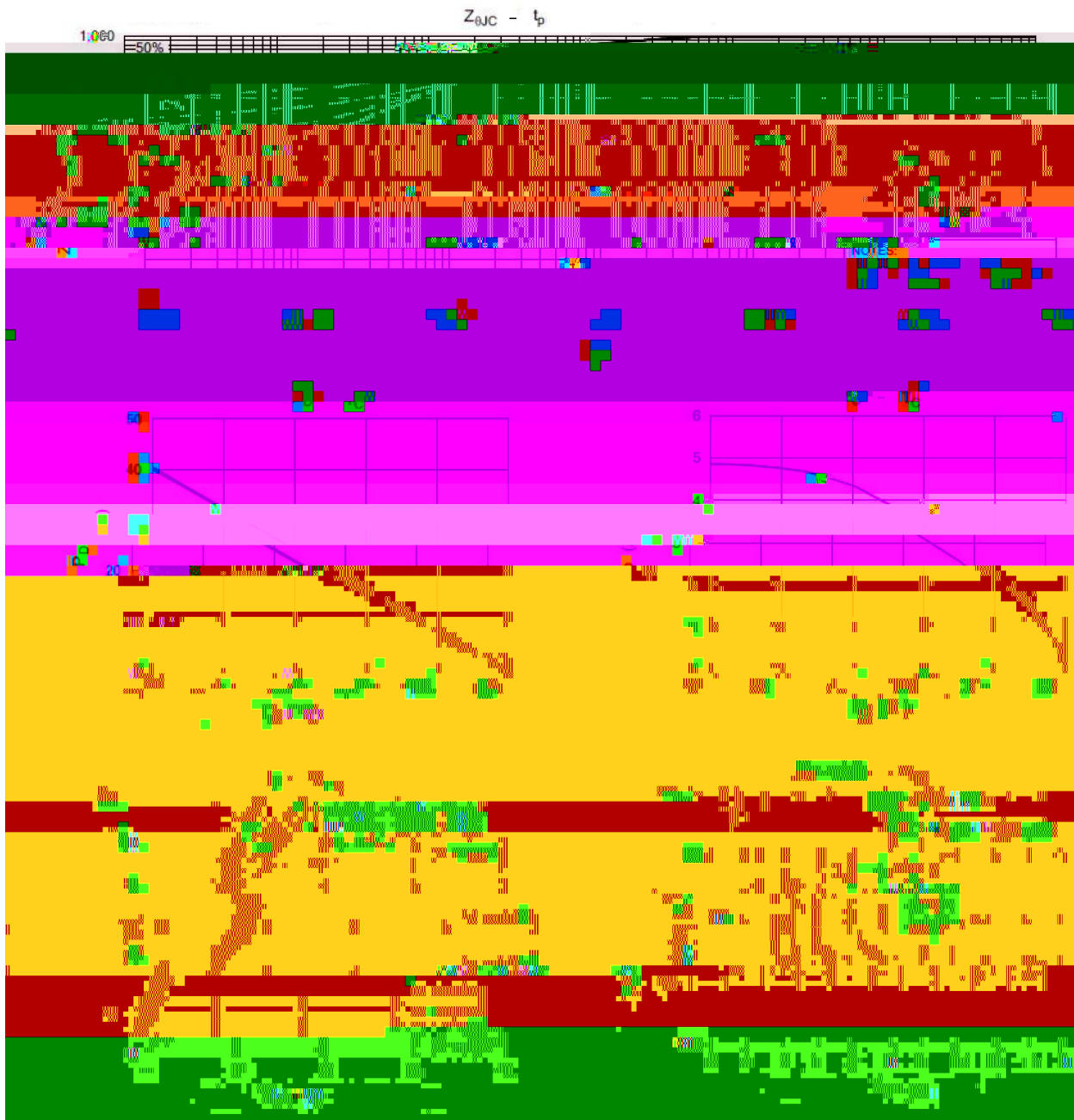
**/  $h_{FE}$  Classifications & Marking**

See Marking Instructions.

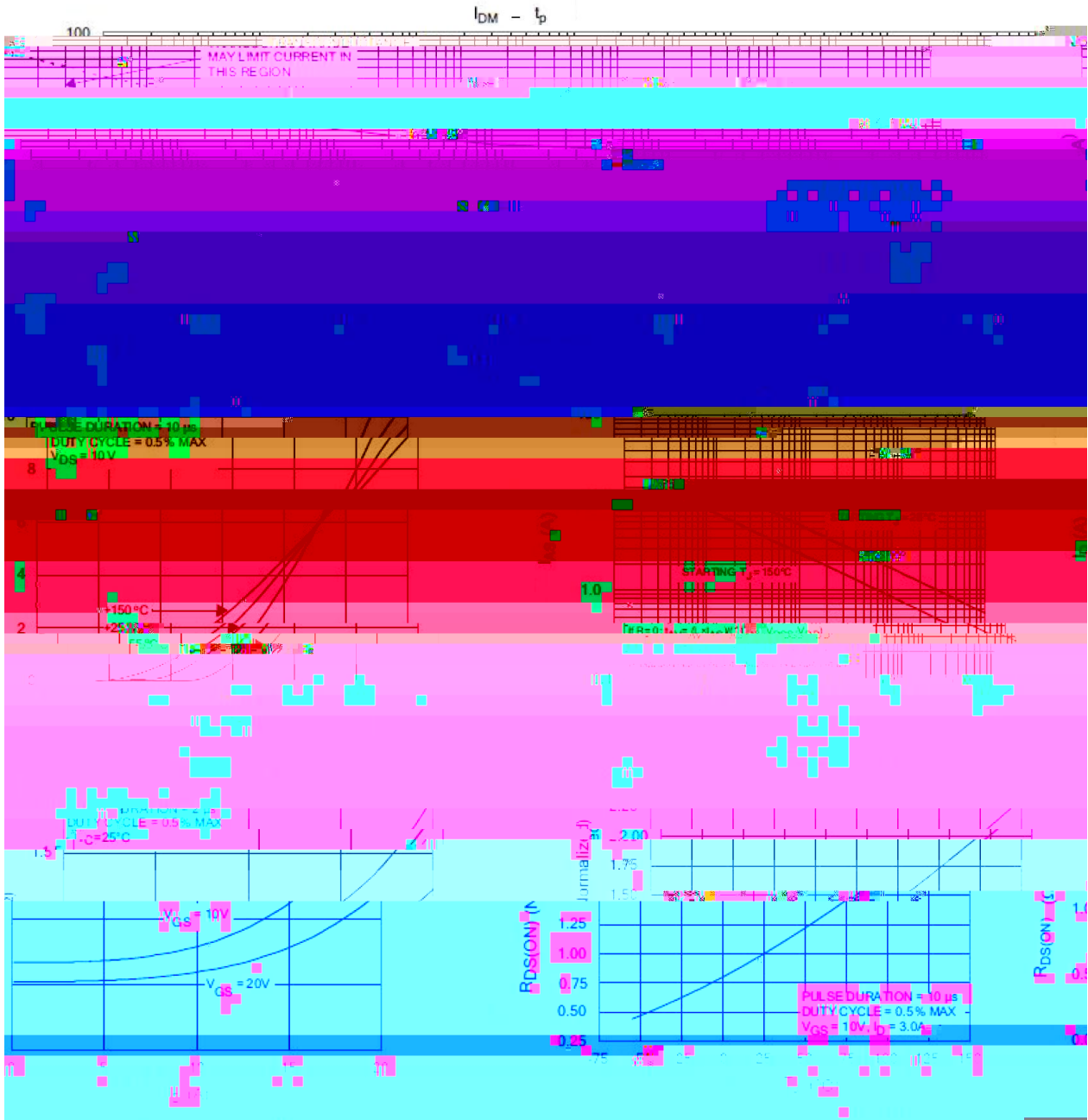
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	200	V
Drain Current	$I_D(Tc=25)$	4.8	A
Drain Current	$I_D(Tc=100)$	3.4	A
Drain Current - Pulsed	$I_{DM}^{a1}$	19.2	A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Avalanche Current	$I_{AR}^{a1}$	1.6	A
Single Pulsed Avalanche Energy	$E_{AS}^{a2}$	125	mJ
Repetitive Avalanche Energy	$E_{AR}^{a1}$	12	mJ
Power Dissipation	$P_D(Tc=25)$	40	W
Derating Factor above 25	$P_D$	0.32	W/
Peak Diode Recovery dv/dt	$dv/dt^{a3}$	5	V/ns

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Capacitance	$C_{iss}$	$V_{DS}=25V$ $V_{GS}=0V$ $f=1MHz$		255		pF
Output Capacitance	$C_{oss}$			52		pF
Reverse Transfer Capacitance	$C_{rss}$			8		pF
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=100V$ $I_D=4.8A$ $R_G=10$ $V_{GS}=10V$		7		ns
Turn-On Rise Time	$t_r$			13		ns
Turn-Off Delay Time	$t_{d(off)}$			27		ns
Turn-Off Fall Time	$t_f$			11		ns
Total Gate Charge	$Q_g$	$V_{DD}=100V$ $I_D=4.8A$ $V_{GS}=10V$		7		nC
Gate to Source Charge	$Q_{gs}$			2		nC
Gate to Drain (" Miller" )Charge	$Q_{gd}$			3		nC
Continuous Source Current (Body Diode)	$I_s$					

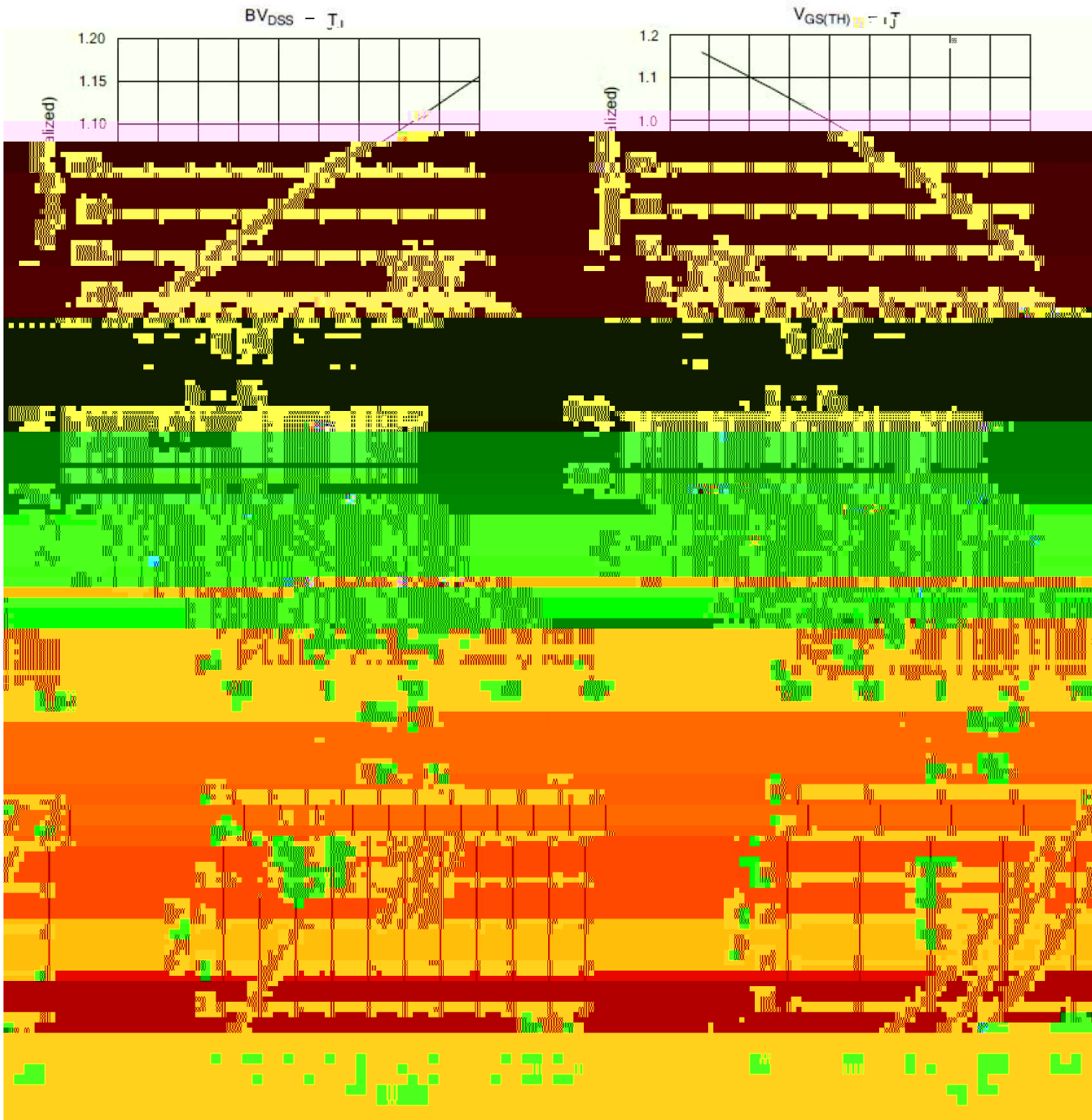
/ Electrical Characteristic Curve



**/ Electrical Characteristic Curve**



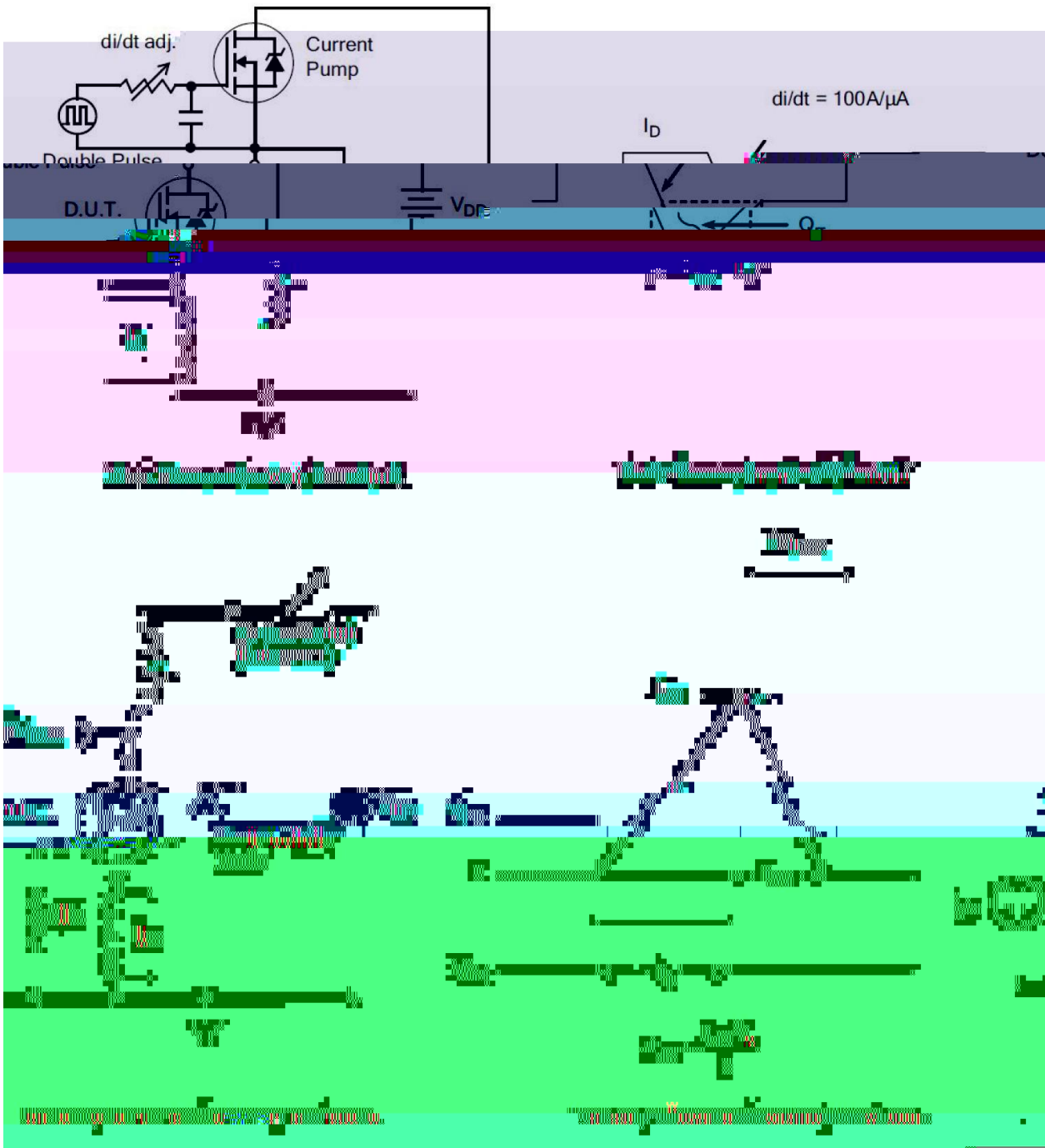
/ Electrical Characteristic Curve



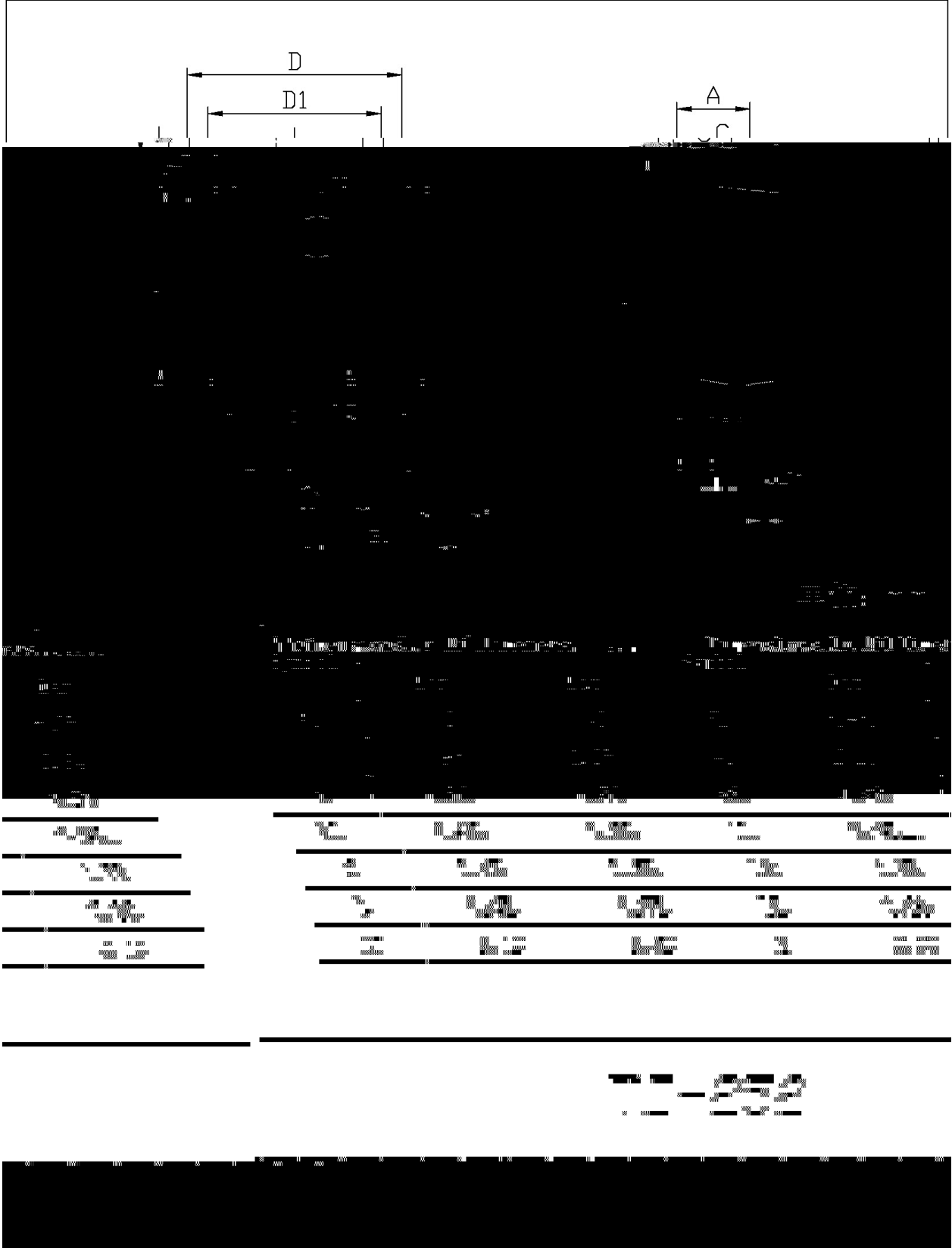
/ Test Circuit and Waveform



/ Test Circuit and Waveform

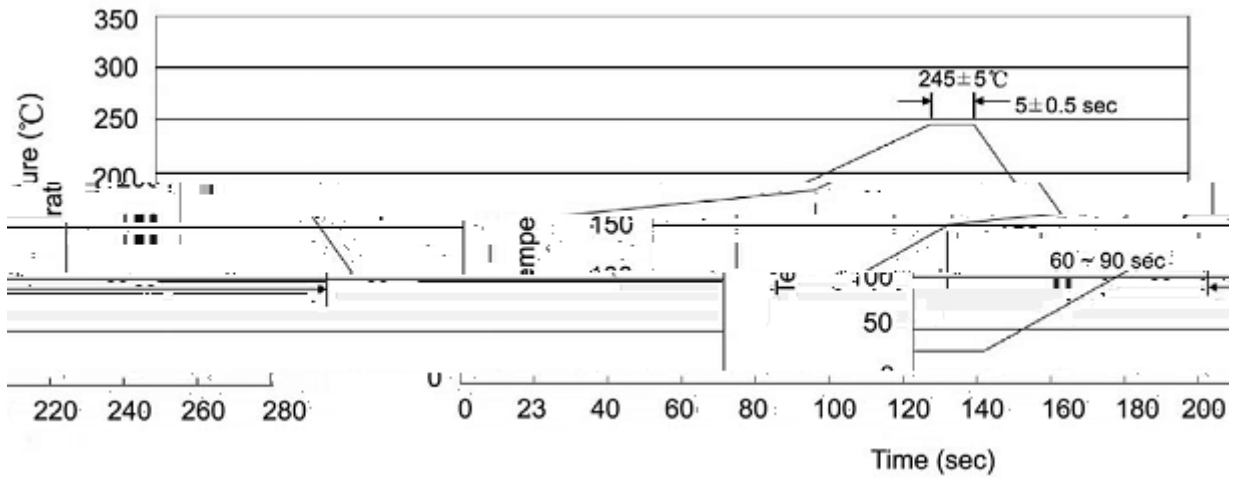


/ Package Dimensions



**BRD5N20**  
Rev.D Nov.-2015

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |        |                                         |
|---|-------|-----|-------|--------|-----------------------------------------|
| 1 | 25    | 150 | 60    | 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     | 5±0.5 | sec;   | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10    | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

2